



Industrial Computing Platform Partner

ARC-615H (HSB-811P) Environment Test Report

Report NO: 05I020017

Issued by: **Rex-Chang** / **11/24/2005**

Test Engineer

Date

Reviewed by: **Wenyuan Yang** / **11/24/2005**

Manager

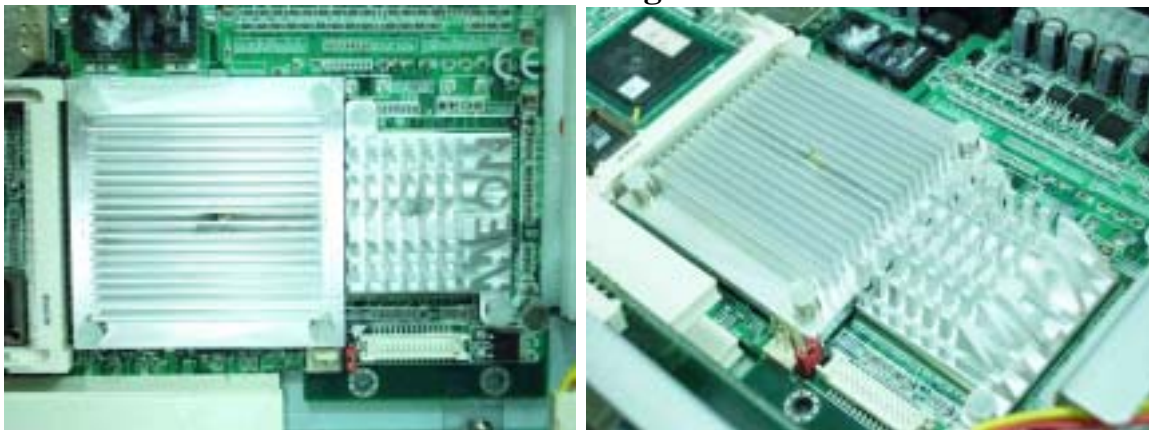
Date

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Num	Item	Spec
1.	Control Box:	ARC- 615H / 1U Rack Mount Chassis
	1. Main Board	AAEON HSB-811P Rev. A1.0 (BIOS: 1.0)
	2. CPU	Intel Celeron – M ULV 600MHz)
	3. Memory	512MB ELPIDA DD2508AMTA
	4. Power Supply	Enhance ENH6020
	5. HDD	Seagate ST340014A 40GB
	6. CD-ROM	NEC CD-2800E
	7. FDD	TEAC FD-235HF

CPU and North Bridge Heat Sink



Temperature cycle test

Test Date: 11-18~21-2005

Test Product: ARC-615H (HSB-811P A1.0) / 1U Rack Mount Chassis

Test Site: AAEON QA Internal Lab.

Performed By: Rex Chang

Test Standard: Reference IEC68-2-14 Testing procedures
Test N: Change of temperature Test

Test Equipment:

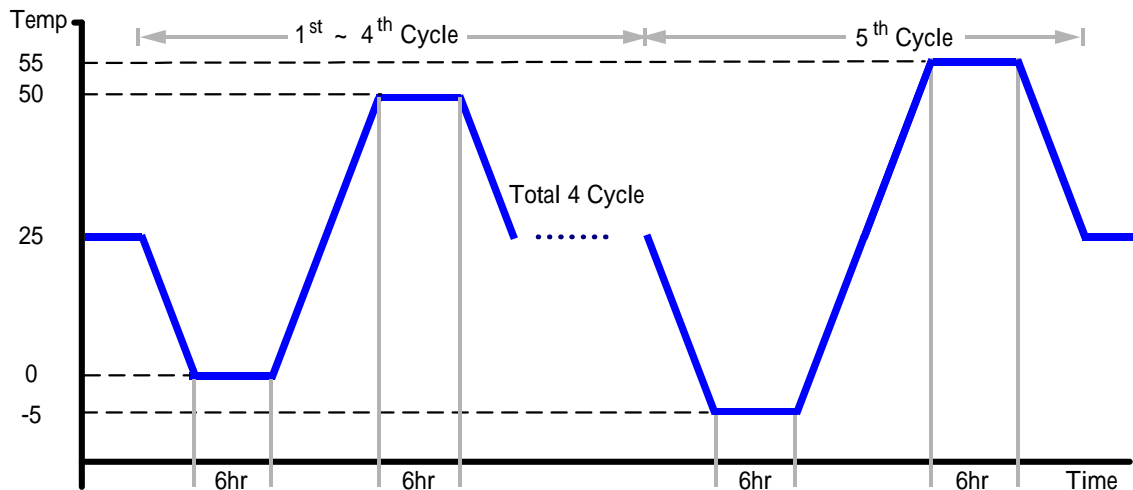
Programmable Temperature & Humidity Chamber
K.SON. INS. TECH. CORP.
Model: THS-D4L+-100
Date of Calibration: 11/30/04
Serial Number: 2582

Temperature Measurement:

20 Channel Thermal Recorder:
YOKOGAWA Inc,
Model: DA100-13-1D
Date of Calibration: 12/25/04
Serial Number: 12A323190

Test Condition:

1. Test Low Temperature: 0 (1~4 cycle)
-5 (5th cycle)
2. Test High Temperature: 50 (1~4 cycle)
55 (5th cycle)
3. Test dwell time: 6Hrs
4. Temperature slope: 2 /min
5. Test cycle: 5 cycle
6. Test Environment Curve:



Temperature cycle test

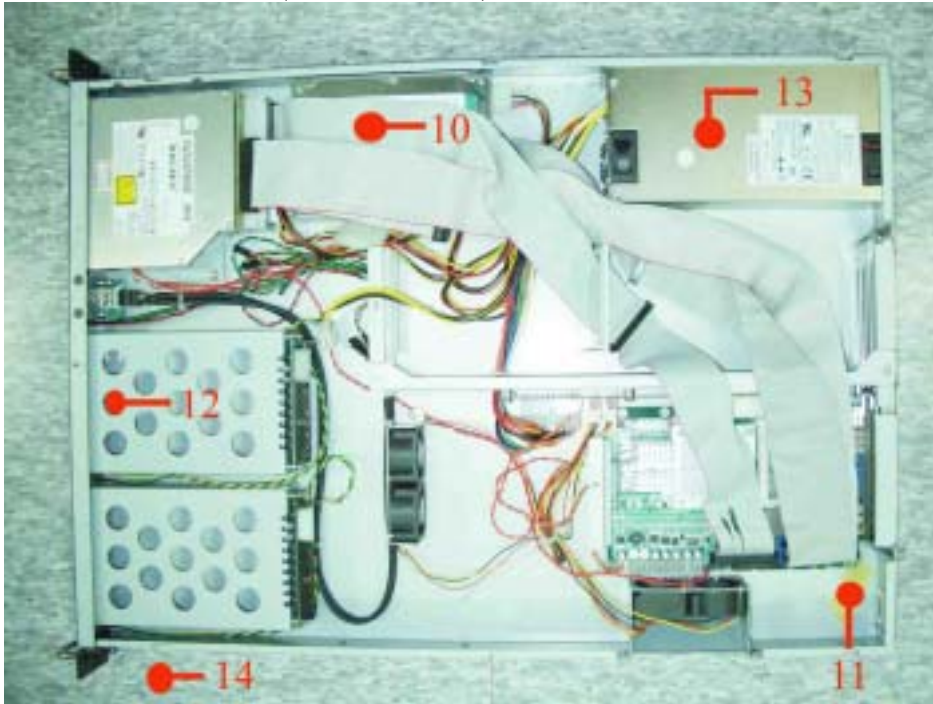
Test O.S. / Software:

Windows 2000 / Run PassMark Burn In Test Pro 4.0

Temperature Recorder:

Measuring Accelerometer Position:

ARC-615H (HSB-811P A1.0) / 1U Rack Mount Chassis



Thermal profile data:

ARC-615H (HSB-811P A1.0) / 1U Rack Mount Chassis

Point	Temp. Stage()	Spec	55	50	25	0	-5
1. CPU1 - INTEL CPU.Celeron-M.ULV 600MHz	100	75.8	70.8	45.8	20.8	15.8	
2. U8 - Intel.RG82852GM Chipset.	110	78.0	73.0	48.0	23.0	18.0	
3. U6 - ICH4.INTEL.FW82801DB Chipset	110	67.9	62.9	37.9	12.9	7.9	
4. U1 - SEMTECH/SC1476ITSTR/IC.Dual Phase PWMController	74	69.8	64.8	39.8	14.8	9.8	
5. L5 - COIL.3.3uH 6.4A.20%.SMD.YC0804-3R3	85	70.4	65.4	40.4	15.4	10.4	
6. L10 - COIL.1.0uH.12.8*12.8*6.5mm.DCR=3mohm Idc=25Amp.ESPI-1206-1R0M	100	69.8	64.8	39.8	14.8	9.8	
7. L9 - COIL.1.0uH.12.8*12.8*6.5mm.DCR=3mohm Idc=25Amp.ESPI-1206-1R0M	100	69.3	64.3	39.3	14.3	9.3	
8. U30 - ClockGenerator.ICS.ICS952607	70	79.0	74.0	49.0	24.0	19.0	
9. Memory	70	69.0	64.0	39.0	14.0	9.0	
10. HDD Surface	55	67.3	62.3	37.3	12.3	7.3	
11. Control Box Inside Air Temperature - 1	N/A	58.9	53.9	28.9	3.9	-1.1	
12. Control Box Inside Air Temperature - 2	N/A	56.9	51.9	26.9	1.9	-3.1	
13. Power Case Surface	50	59.9	54.9	29.9	4.9	-0.1	
14. Chamber Air Temperature	N/A	55.3	50.3	25.3	0.3	-4.7	

Note: The description in red states which temperature is over the specification of the device.

Temperature cycle test

Sample Configuration & Quantity Under Test:

Quantity: 1 (ARC-615H / 1U Rack Mount Chassis)

Test Result:

The system structure doesn't deformation; Function is passed during system test.

Cold Start test

Test Date: 12-01~02-2005

Test Product: ARC-615H (HSB-811P A1.0) / 1U Rack Mount Chassis

Test Site: AAEON QA Internal Lab.

Performed By: Rex Chang

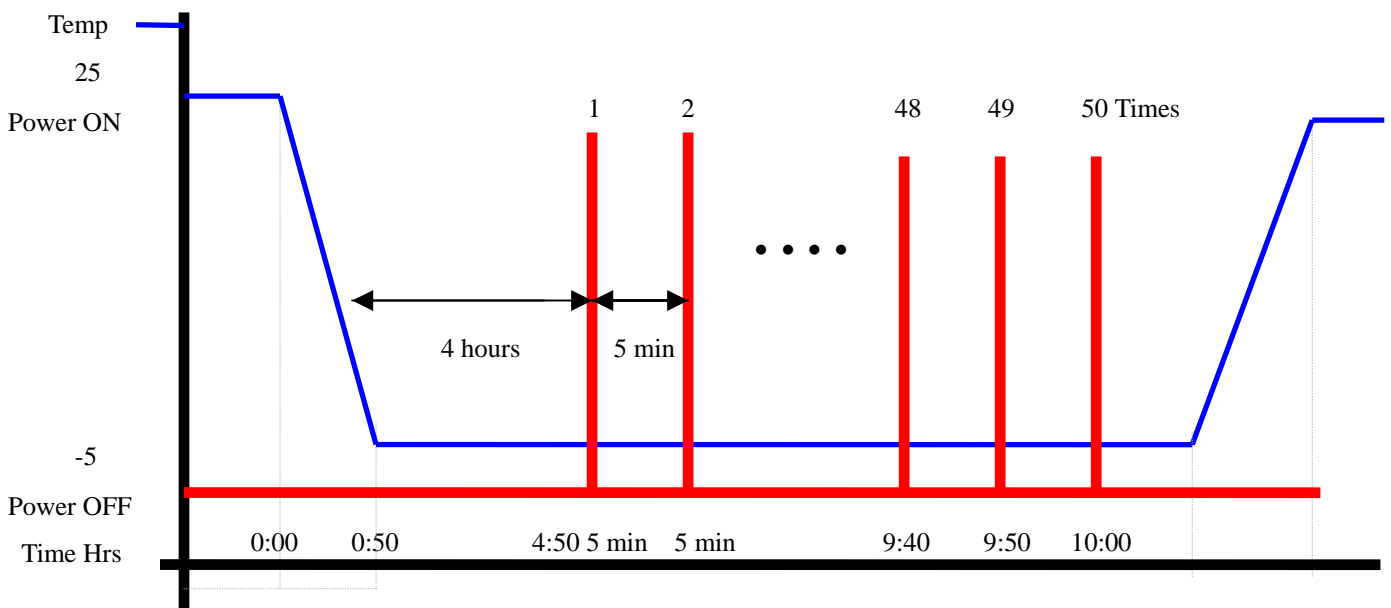
Test Standard: Reference IEC 68-2-1 Testing procedures
Test Ab: Cold Test

Test Equipment:

Programmable Temperature & Humidity Chamber
K.SON. INS. TECH. CORP.
Model: THS-D4H+-100
Date of Calibration: 05/23/05
Serial Number: 1241

Test Condition:

1. Test Temperature: -5
2. Test Times: 5 Hours or 50 times of ON/OFF
 - (1) Power off for 4 hours before 1'st power on. Then once complete boot, power off immediately.
 - (2) After 5 min later power on again and wait until booting is completed.
 - (3) Repeat (2) for around 4:50
 - (4) Power off then wait for 5 min before final power on operation.
3. Number of test: 50 times
4. Test Software: Windows 2000
5. Test Environment Curve:



Sample Configuration & Quantity Under Test:

Quantity: 1 (ARC-615H / 1U Rack Mount Chassis)

Test Result:

Passed.

High temperature storage test

Test Date: 11-21~23-2005

Test Product: ARC-615H (HSB-811P A1.0) / 1U Rack Mount Chassis

Test Site: AAEON QA Internal Lab.

Performed By: Rex Chang

Test Standard: Reference IEC 68-2-2 Testing procedures
Test Bb: Dry Heat Test (Non-operation)

Test Equipment:

Programmable Temperature & Humidity Chamber
K.SON. INS. TECH. CORP.
Model: THS-D4L+-100
Date of Calibration: 11/30/04
Serial Number: 2582

Testing Item:

1. Test Temperature: 60
2. Test Times: 48Hrs
3. Test Environment Curve:



Sample Configuration & Quantity Under Test:

Quantity: 1 (ARC-615H / 1U Rack Mount Chassis)

Test Result:

1. After high temperature storage test, the structure of chassis never change shape and surface paint doesn't flake off.
2. The system all functions are OK after high temperature storage test.

High temperature storage test

Test Date: 11-16~18-2005

Test Product: ARC-615H / 1U Rack Mount Chassis

Test Site: AAEON QA Internal Lab.

Performed By: Rex Chang

Test Standard: Reference IEC 68-2-2 Testing procedures
Test Bb: Dry Heat Test (Non-operation)

Test Equipment:

K.SON. INS. TECH. CORP.
Model: THS-D4L+-100
Date of Calibration: 11/30/04
Serial Number: 2582

Testing Item:

- 4. Test Temperature: 80
- 5. Test Times: 48Hrs
- 6. Test Environment Curve:



Sample Configuration & Quantity Under Test:

Quantity: 1 (ARC-615H / 1U Rack Mount Chassis)

Test Result:

After high temperature storage test, the structure of chassis never change shape and surface paint doesn't flake off.

Low temperature storage test

Test Date: 11-14~16-2005

Test Product: ARC-615H (HSB-811P A1.0) / 1U Rack Mount Chassis

Test Site: AAEON QA Internal Lab.

Performed By: Rex Chang

Test Standard: Reference IEC 68-2-1
Testing procedures Test Ab: Cold Test (Non-operation)

Test Equipment:

Programmable Temperature & Humidity Chamber
K.SON. INS. TECH. CORP.
Model: THS-D4L+-100
Date of Calibration: 11/30/04
Serial Number: 2582

Testing Item:

1. Test Temperature: -20
2. Test Times: 48Hrs
3. Test Environment Curve:



Sample Configuration & Quantity Under Test:

Quantity: 1 (ARC-615H / 1U Rack Mount Chassis)

Test Result:

1. After high temperature storage test, the structure of chassis never change shape and surface paint doesn't flake off.
2. The system all functions are OK after low temperature storage test.

Humidity test

Test Date: 11-24~26-2004

Test Product: ARC-615H (HSB-811P A1.0) / 1U Rack Mount Chassis

Test Site: AAEON QA Internal Lab.

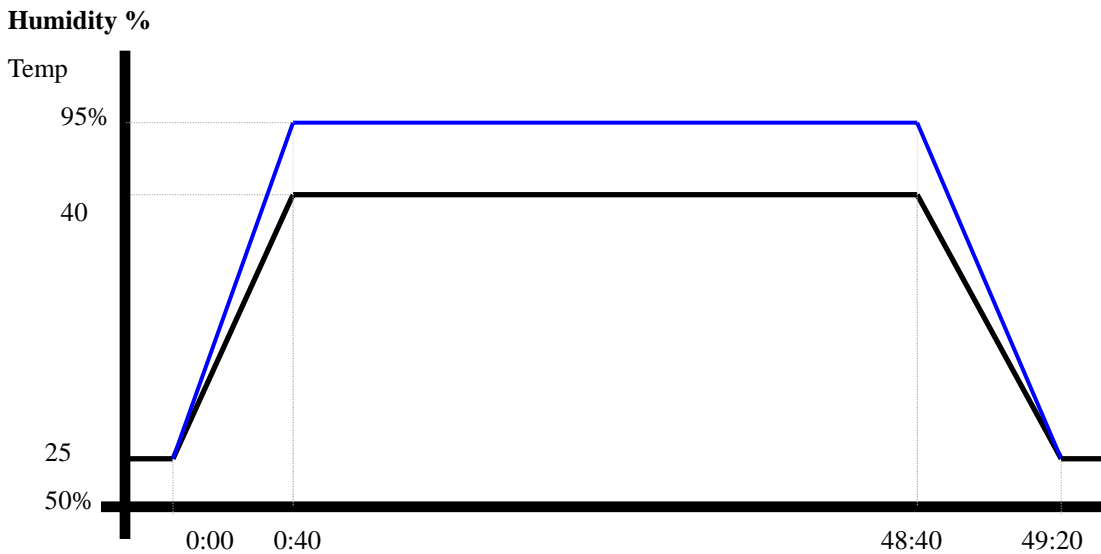
Performed By: Rex Chang

Test Standard: Reference IEC 68-2-3 Testing procedures
Test Ca: Damp heat, steady state (Non-operation)

Test Equipment:
Programmable Temperature & Humidity Chamber
K.SON. INS. TECH. CORP.
Model: THS-D4L+-100
Date of Calibration: 11/30/04
Serial Number: 2582

Testing Item:

1. Test Temperature: 40
2. Test Humidity: 95%RH
3. Test Times: 48Hrs
4. Test Environment Curve:



Sample Configuration & Quantity Under Test:
Quantity: 1 (ARC-615H / 1U Rack Mount Chassis)

Test Result:

1. After high temperature storage test, the structure of chassis never change shape and surface paint doesn't flake off.
2. The system all functions are passed after humidity storage test.